

IN THE CLAIMS:

1-85 (Cancelled)

86 (Amended): A method of coupling signals between electronic devices in a modular electronic system, said method comprising the steps of:

locating a first co-planar subset of said electronic devices on a first planar semiconductor chip;

locating a second co-planar subset of said electronic devices on a planar second semiconductor chip; and,

aligning and affixing said first and second chips so as to capacitively couple said first and second chips.

87 (Original): A method of coupling signals between electronic devices in a modular electronic system as defined in claim 86 wherein the first and second chips are affixed to a base substrate thereby capacitively coupling said first and second chips via said substrate.

88-99. (Cancelled)

100 (Amended): A method of capacitively coupling signals between first and second semiconductor planar chips, each said chip having a plurality of planar half-capacitors, said method comprising the steps of:

affixing said first planar chip to a substrate;

aligning said second planar chip to said first chip; and,

affixing said second planar chip to said substrate, thereby capacitively coupling corresponding half-capacitors on said first and second planar chips and providing direct capacitive coupling between said first and second planar chips.

101-205. (Cancelled)